



DMN2250UFB

N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on) max}	Ι _D T _A = +25°C
	0.17Ω @ V _{GS} = 4.5V	1.35A
20V	0.23Ω @ V _{GS} = 2.5V	1.15A
	0.25Ω @ V _{GS} = 1.8V	1.10A

Description

This new generation MOSFET has been designed to minimize the onstate resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- **Power Management Functions**

Features

- Low On-Resistance
- Very Low Gate Threshold Voltage VGS(TH), 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 @4

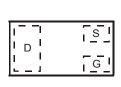
C

Weight: 0.001 grams (approximate)



X1-DFN1006-3

Bottom View



Top View Internal Schematic

Drain Body Diode Gate Gate Protection Source Diode

Equivalent Circuit

Ordering Information (Note 4)

ESD PROTECTED

Part Number	Case	Packaging
DMN2250UFB-7B	X1-DFN1006-3	10,000/Tape & Reel

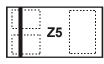
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. Notes:

2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and

<1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



Z5 = Product Type Marking Code Bar Denotes Gate and Source Side

Top View



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 5) V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	ID	1.35 1.03	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I _{DM}	6	A
Maximum Body Diode continuous Current			ls	1	А

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Total Power Dissipation (Note 5)	T _A = +25°C	Р	0.5	W	
Total Power Dissipation (Note 5)	T _A = +70°C	PD	0.3	٧V	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	$R_{ ext{ heta}JA}$	278	°C/W	
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

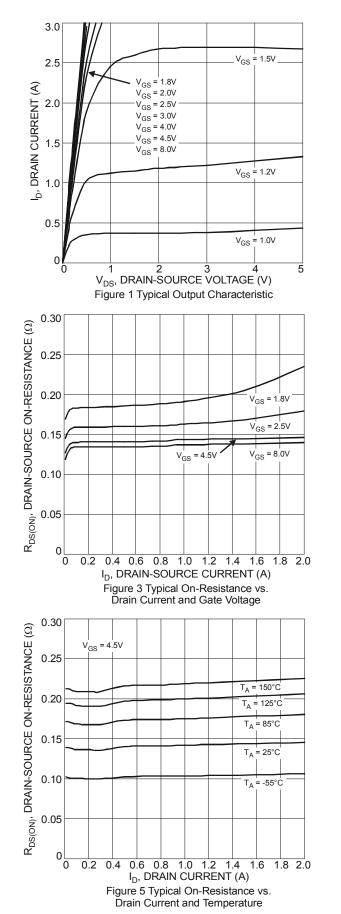
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

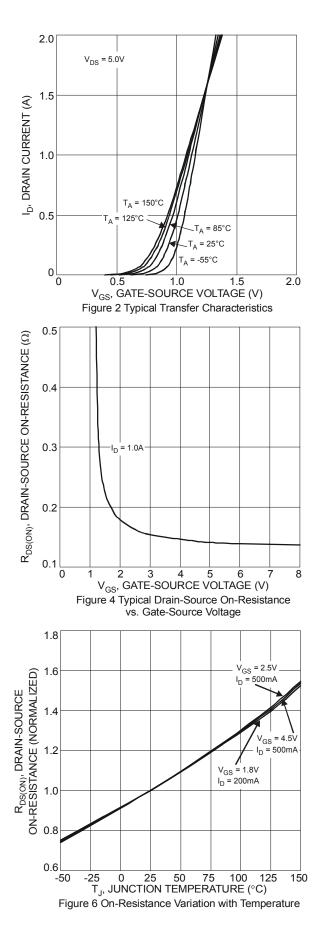
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)	Symbol	IVIIII	тур	Wax	Unit	Test condition	
Drain-Source Breakdown Voltage	BV _{DSS}	20		_	V	V _{GS} = 0V, I _D = 250µA	
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$	IDSS	_		100	nA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	—	±1	μA	$V_{GS} = \pm 6V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)	000						
Gate Threshold Voltage	V _{GS(th)}	0.35	—	1.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
			—	170		V _{GS} = 4.5V, I _D = 1A	
Static Drain-Source On-Resistance	R _{DS (ON)}	_		230	mΩ	V _{GS} = 2.5V, I _D = 1A	
			—	250		V _{GS} = 1.8V, I _D = 1A	
Forward Transfer Admittance	Y _{fs}	—	1.4	—	S	V _{DS} = 10V, I _D = 1A	
Diode Forward Voltage	V _{SD}	_	0.7	1.2	V	V _{GS} = 0V, I _S = 150mA	
DYNAMIC CHARACTERISTICS (Note 7)				-			
Input Capacitance	Ciss		94	_	pF	(-10)(-10)(-0)(-0)(-0)(-0)(-0)(-0)(-0)(-0)(-0)(-	
Output Capacitance	Coss	-	12	_	pF	V _{DS} =16V, V _{GS} = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}		10		pF		
Gate resistance	Rg		87.1		Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg		1.4	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	3.1	_	nC	(1 - 10)(1 - 250m)	
Gate-Source Charge	Qgs	—	0.13	—	nC	V _{DS} = 10V, I _D = 250mA	
Gate-Drain Charge	Q _{gd}	_	0.14	_	nC		
Turn-On Delay Time	t _{D(on)}	_	4.3	_	ns		
Turn-On Rise Time	tr	_	6.1	—	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(off)}	_	59.4	_	ns	R _L = 47Ω, R _G = 10Ω, I _D = 200mA	
Turn-Off Fall Time	tf		25.4	_	ns		

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing. Notes:

DMN2250UFB



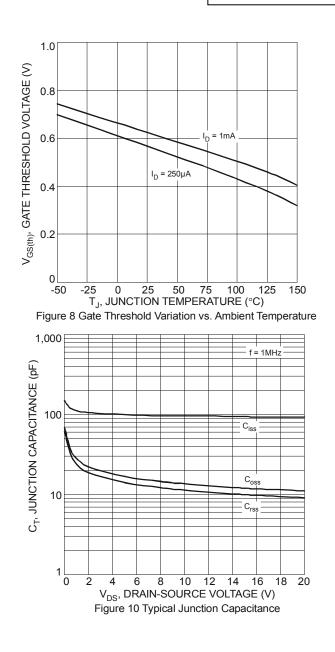






NEW PRODUCT

0.30 $R_{\text{DS}(\text{ON})^{\prime}}$ DRAIN-SOURCE ON-RESISTANCE ($\Omega)$ V_{GS} = 1.8V I_D = 200mA 0.25 $V_{GS} = 2.5V$ $I_D = 500mA$ 0.20 V_{GS} = 4.5V I_D = 500mA 0.15 0.10 0.05 0 75 100 125 -50 -25 0 25 50 T_J, JUNCTION TEMPERATURE (°C) Figure 7 On-Resistance Variation with Temperature 2.0 1.8 1.6 I_S, SOURCE CURRENT (A) 1.4 1.2 1.0 0.8 150° 0.6 = 85°C 0.4 = 25°C 0.2 = -55°C 0 ō 0.3 0.6 0.9 V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9 Diode Forward Voltage vs. Current 10 V_{GS} GATE THRESHOLD VOLTAGE (V) 8 $V_{DS} = 10V$ $I_{D} = 250mA$ 6 4



0.5

5 1.0 1.5 2.0 2.5 Q_g, TOTAL GATE CHARGE (nC)

Figure 11 Gate Charge

2

0

0

3.0

3.5

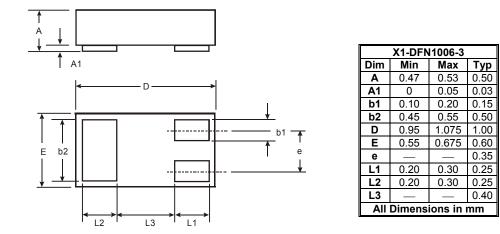
150

1.2



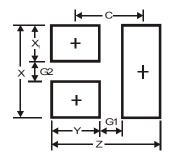
Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
Х	0.7
X1	0.25
Y	0.4
С	0.7



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2013, Diodes Incorporated

www.diodes.com

单击下面可查看定价,库存,交付和生命周期等信息

>>Diodes Incorporated(达迩科技(美台))